EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S65	184	((test or tested or testing) near (pad or pads)) near8 (inactive or surround or surrounding or surrounded or periphery or peripheral or outside or edge) near8 (die dice chip element component IC "integrated circuit")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/09 08:44
S66	7869	(test or testing or tested or dummy) near (pad or pads)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/09 08:44
S67	138	S65 and ((@ad<"20020122") or (@rlad<"20020122"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/09 08:55
S68	14991561	(die or dice or element or device or component or IC or "integrated near circuit")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/09 08:54
S69	4177	S66 same S68	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/09 08:54
S70	1512	S69 same (substrate or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/09 08:54
S71	1071	S70 and ((@ad<"20020122") or (@rlad<"20020122"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/09 08:55

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	992	(bond near pad) near8 (input or contact or bond or bonding or bonded) near8 (test or tested or testing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/09 17:07
L2	14991561	(die or dice or element or device or component or IC or "integrated near circuit")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/09 17:11
L3	826	1 same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/09 17:13
L4	374	(438/786).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/09 17:50
L5	447	(438/619).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/09 17:51